

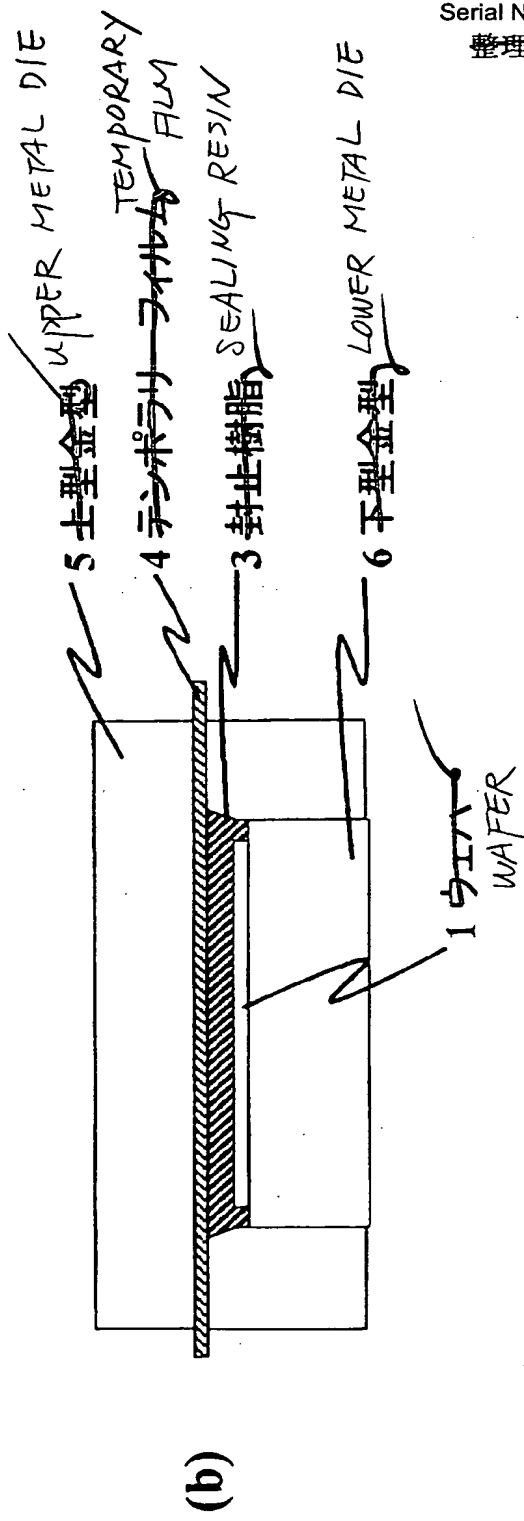
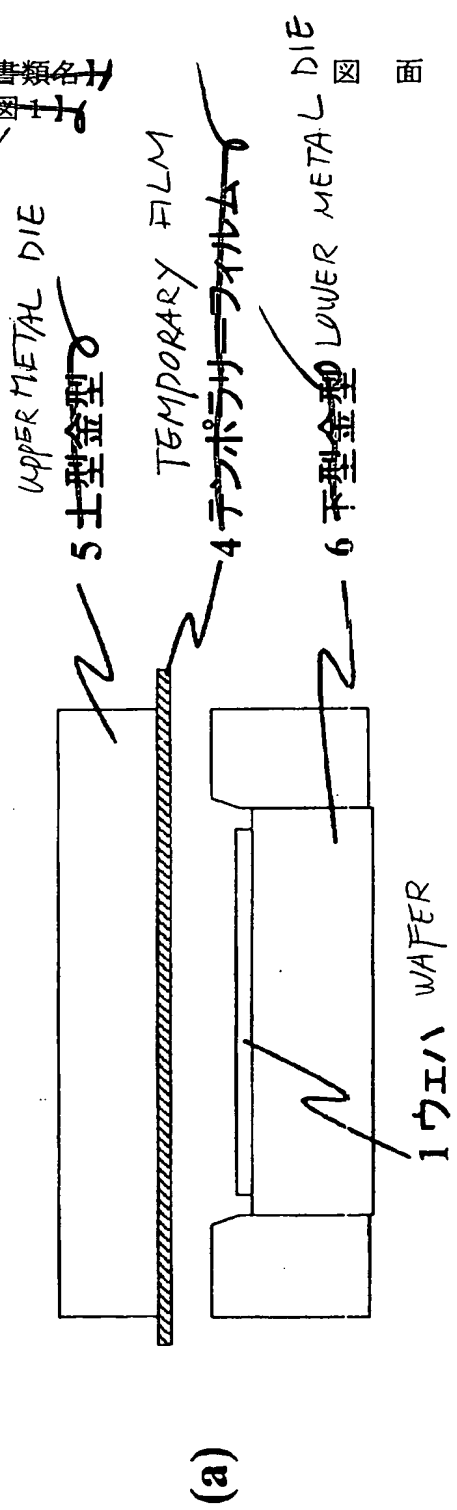
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Serial No.: 09/686,958  
 整理番号: 00-40650

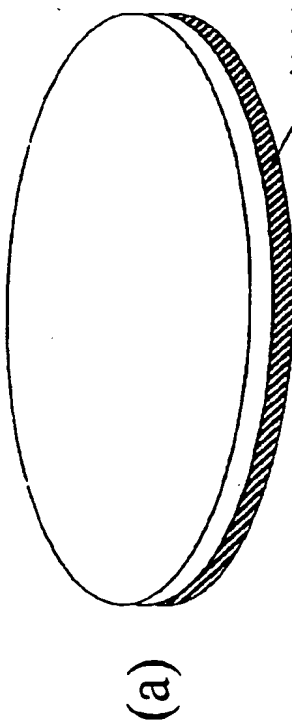
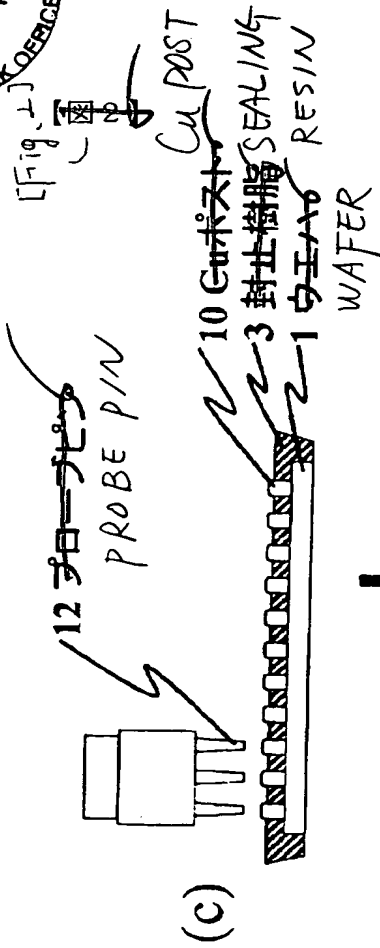
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 MKL  
 9/30/02

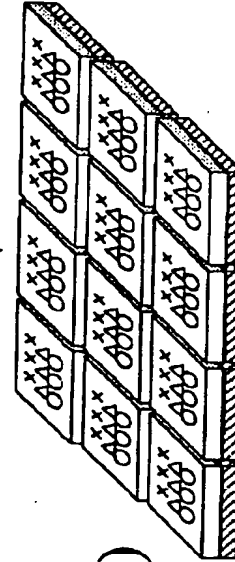
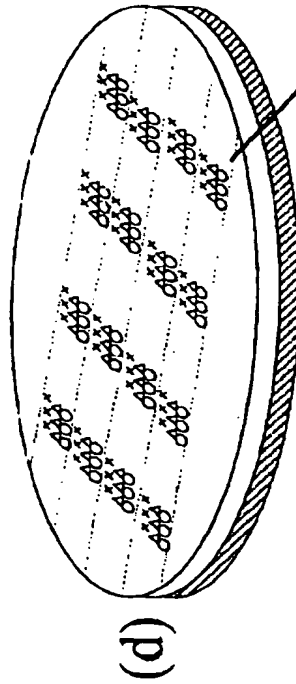
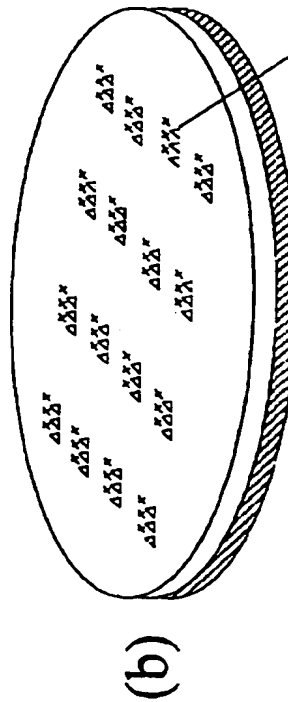
Fig. 1  
 【書類名】  
 【図】



面



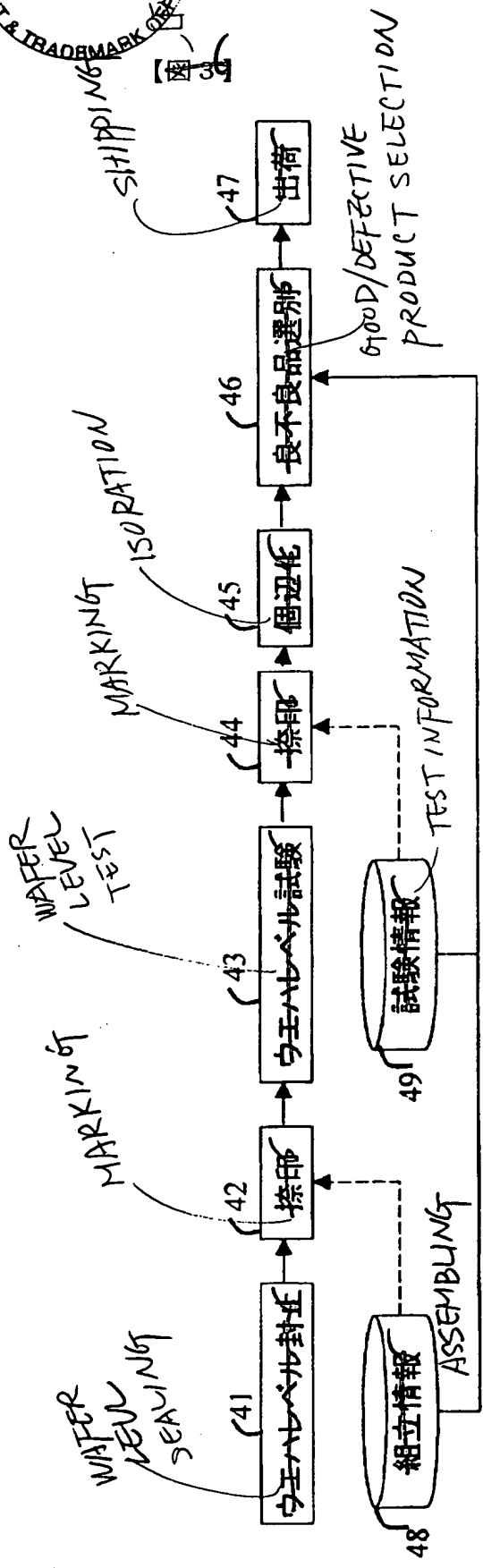
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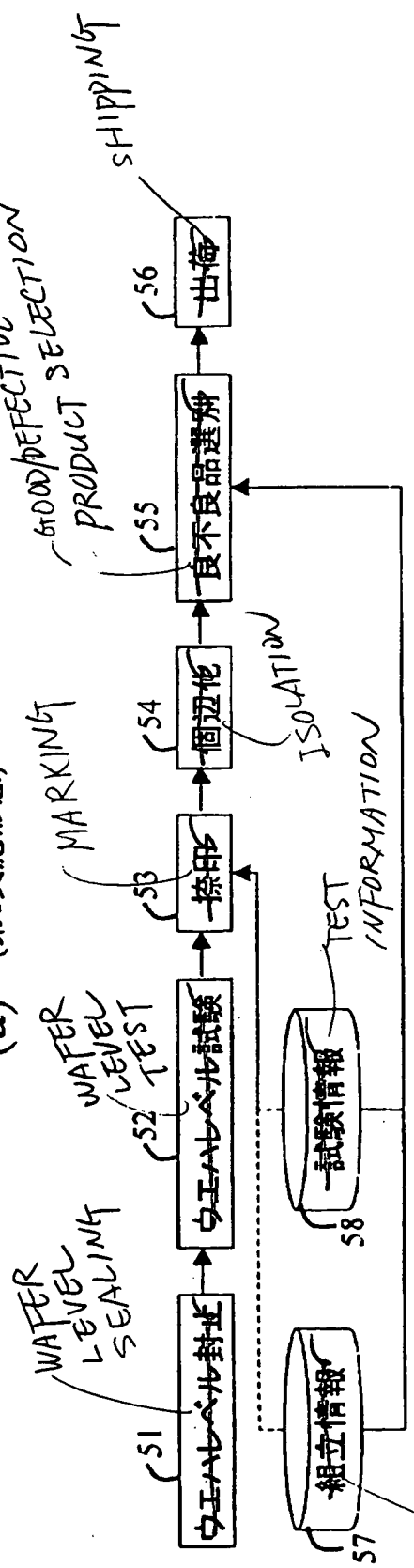
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(a) (第1実施形態) FIRST EMBODIMENT



(b) (第2実施形態) SECOND EMBODIMENT

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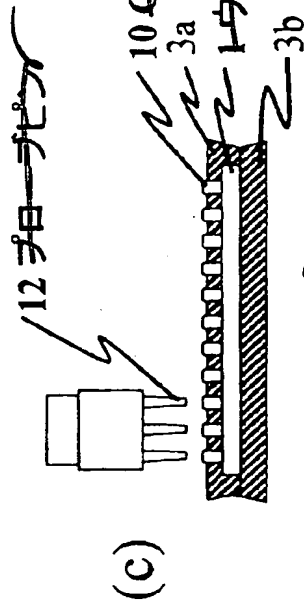
[Fig. 4]



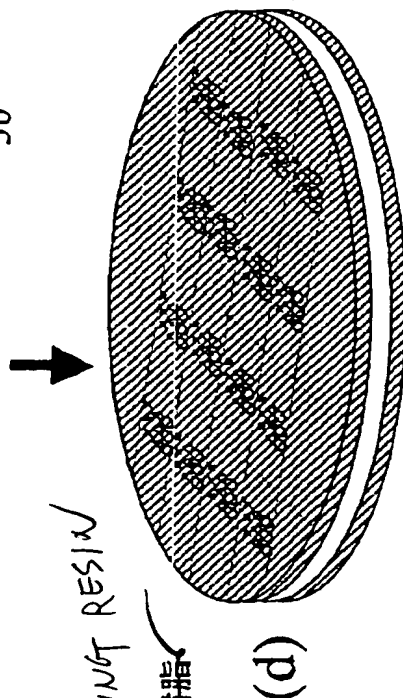
Serial No. 09/686,958  
 整理番号: 00-40650

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 9/30/02

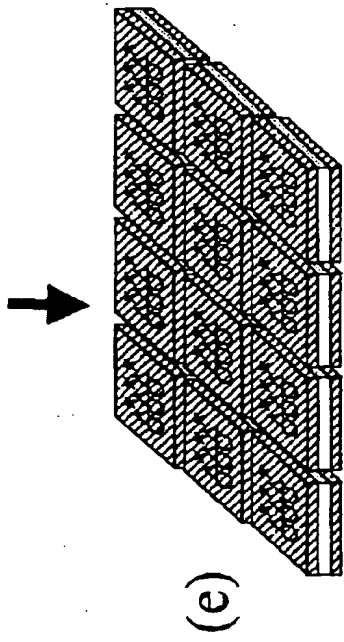
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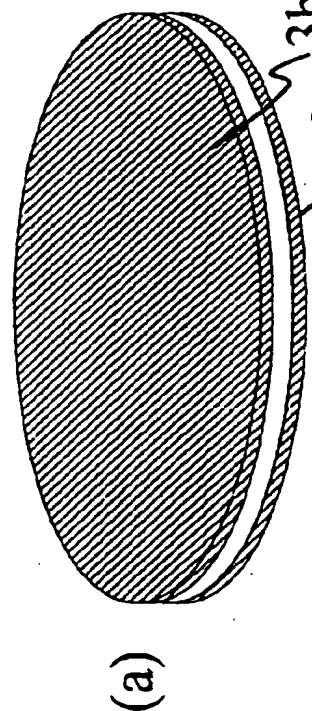
(c)



(d)

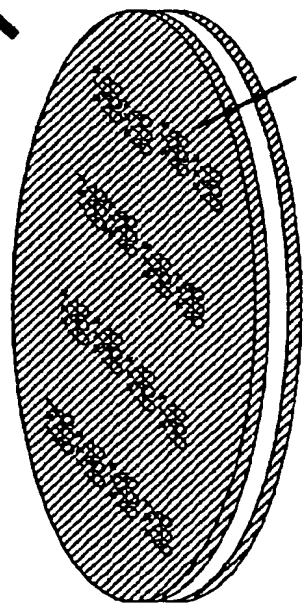


(e)



(a)

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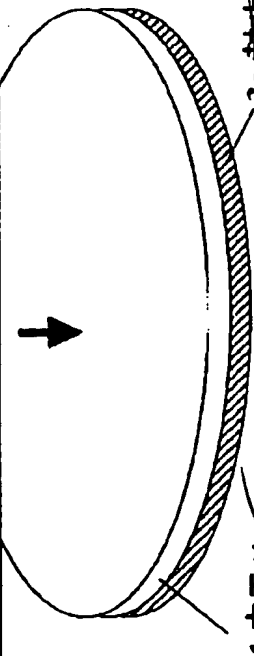
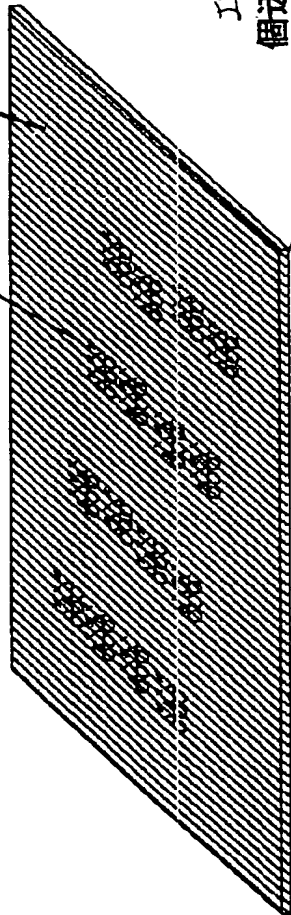
[Fig. 5]

図 5

INFORMATION

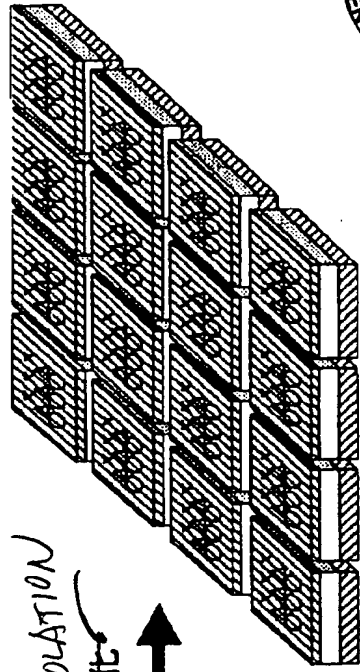
MARKING  
MANUFACTURING  
捺印製造情報

樹脂シート  
RESIN SHEET



ウェハ  
WAFER

3a 封止樹脂  
SEALING RESIN



ISOLATION  
個辺化



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